

Description

The SiT91281 is a low jitter, automotive grade clock generator engineered for automotive applications where reliability and environmental robustness are critical. It comes with a single clock domain, 4 configurable differential or 8 single-ended low skew outputs, and clock status/alarm reporting.

The SiT91281 integrates SiTime's MEMS resonator, eliminating the need for an external oscillator or resonator. This integrated MEMS improves system reliability by eliminating traditional clock generators' dependence on quartz and its associated issues like high failure rates and matching requirements.

The device is configurable in output frequency, output style (differential and LVCMOS) and individual Output Enables through the serial interface. Internal monitoring features help improve system Functional Safety metrics by using the General Purpose I/O (GPIO) pins and device registers to report fault conditions to a safety manager MCU.

The SiT91281 is compliant with PCIe Generation 1-6 including configurable spread-spectrum clocking.

User-defined, pre-programmed and user-programmable Non-volatile memory (NVM) enables a high degree of flexibility and defined startup-configuration. Configurable GPIO pins support state changes such as individual output enable selection.

Block Diagram

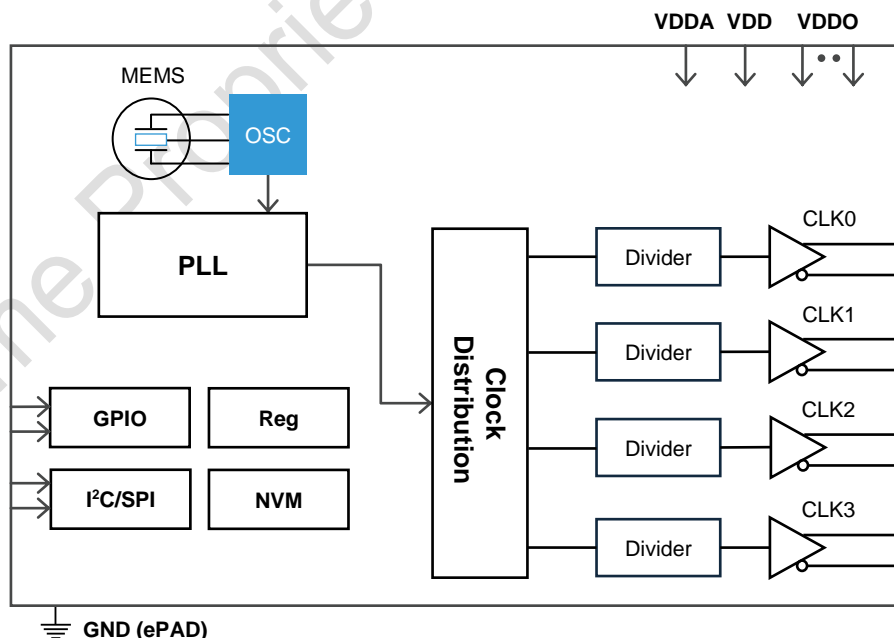


Figure 1. SiT91281 Block Diagram

Features

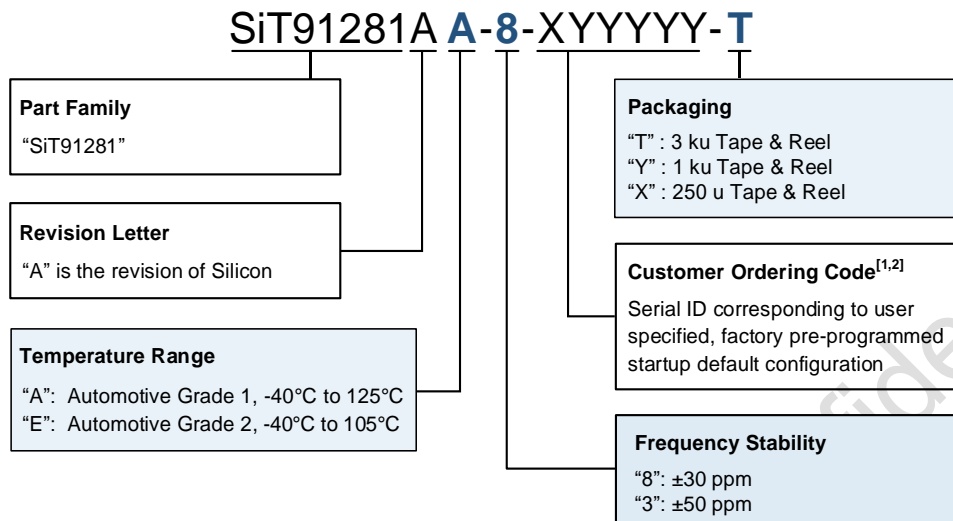
- Frequencies from 1 MHz to 700 MHz
- Fully integrated MEMS-based clock source
- Configurable clock domain and 4 differential outputs or 8 single-ended outputs
- AEC-Q100 Grade 1, -40°C to 125°C
- Excellent frequency stability:
 - ± 50 ppm (-40°C to 125°C)
 - ± 20 ppm (-40°C to 105°C)
 - [Contact SiTime](#) for ± 30 ppm (-40°C to 125°C)
- Clock fault monitors (Loss of Lock, Loss of MEMS clock, Output Driver Errors, Die Temperature)
- Supply voltage of 1.8 V to 3.3 V
- Configurable spread-spectrum clock generation
- Low phase jitter, 200 fs maximum (12 kHz-20 MHz)
- PCIe Gen 1 to 6 compliant
- Resistant to shock/vibration
- QFN 24 pin 4 x 4 mm, 0.5 mm pitch (wetable flank) package

Applications

- ADAS Computer, Zonal ECU, Domain ECU
- Lidar, Radar Sensors
- Automotive High-Speed Networking and SerDes
- Infotainment/Digital Cockpit systems

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Ordering Information**Notes:**

- X = "A" and "B" customer device, "C" to "Z" reserved.
A: Denotes blank devices.
B: Denotes Pre-configured devices, [contact SiTime](#) for the specifics.
- Y = 0..9, A...Z for custom serial ID.

Functional Description

The SiT91281 is an automotive Grade 1 low-jitter clock generator with an integrated SiTime MEMS resonator, capable of providing 4 configurable differential or 8 single-ended low skew outputs, or a combination of both. Differential outputs can be configured up to 700 MHz, while single ended outputs can be configured up to 220 MHz. Due to the integrated MEMS resonator, the device can be operated without the need for any external crystal or oscillator reference or associated matching requirements.

The output drivers support commonly used signal formats, such as LVPECL, LVDS, HCSL, LVCMOS, as well as FlexSwing. Individual VDDO pins capable of accepting between 1.8 V and 3.3 V are available for each differential output driver. The core voltage supply (VDD) accepts 3.3 V, 2.5 V, or 1.8 V and is independent from the output supplies (VDDOx).

The SiT91281 combines SiTime's highly reliable MEMS resonator with a wideband PLL, on-chip temperature compensation, and four integer dividers to generate high-performance outputs with typical jitter of 150 fs and frequency stability of ± 20 ppm (-40°C to 105°C) or ± 30 ppm (-40°C to 125°C). The SiT91281's on-chip regulators ensure extremely good power supply noise rejection, ensuring minimal deviation from the jitter specification due to power supply noise. Spread spectrum modulation is available in the SiT91281, to help reduce electromagnetic interference (EMI) by spreading output clock energy over a broader range.

The elimination of an external reference leads to improved ease of use by removing any matching or frequency jump issues. Importantly for safety critical automotive

applications, all dependence on crystals prone to high failure rates is eliminated. In addition to improved failure rates, internal functions such as the MEMS reference clock, bandgap reference, PLL, and VDDIOs, and output drivers are monitored. This is a significant improvement over traditional status monitoring of only the reference input. Fault conditions on these monitored functions can be configured to be sent out to GPIO outputs individually or as a combined alarm signal or read via I2C or SPI interface. This allows an external safety manager MCU to be alerted to a fault condition in the clock generator to take appropriate action consistent with system level safety goals.

The SiT91281 is available optionally with or without a serial interface (I2C or SPI). The serial interface can be used to read internal registers, including status of the internal monitoring functions. A user can use In-System Configuration (ISC) mode to write to contents of internal registers to modify the device configuration via the serial interface. In such a use case, the modified configuration will be lost at the next power cycle. The SiT91281 allows the user to burn the new configuration into the NVM via the In-System Programming (ISP) Mode, which will then be the new default configuration at the next power cycle.

Optionally, the user can store up to four different static clock configurations in the SiT91281 NVM, one of which is selectable based on the status continuously sampled on the two Frequency Select pins.

For applications which require only a standard configuration, the SiT91281 is also available as a factory configured device without a serial interface, which allows the use of the serial interface pins as additional GPIOs. SiTime will program the NVM to configure the devices according to specific customer requirements.

SiT91281 Low Jitter, 4-Output, AEC-Q100 MEMS Clock Generator

Chip Status Monitoring

The SiT91281 monitors multiple internal parameters and makes these status monitoring functions available to an external MCU via GPIO pins or through direct access of internal registers via I2C/SPI. All the status signals listed in the table below are also accessible via register reads over the serial interface (I2C or SPI).

Table 1. Chip Status Monitoring Signals

Monitoring Function	Monitored on GPIO Pin (Parts without I2C/SPI)	Monitored on GPIO Pin (Parts with I2C/SPI)	Function
MEMS Clock Monitor	Pin 2 / 3 / 4 / 6 / 7 / 23 / 24	Pin 2 / 3 / 23 / 24	Goes low when internal MEMS clock does not oscillate
Bandgap Monitor	Pin 2 / 3 / 4 / 6 / 7 / 23 / 24	Pin 2 / 3 / 23 / 24	Goes low when internal band gap reference falls below threshold
PLL Lock Monitor	Pin 2 / 3 / 4 / 6 / 7 / 23 / 24	Pin 2 / 3 / 23 / 24	Goes low when PLL loses lock with MEMS reference clock
Clock0 Ready	Pin 2	Pin 2	Goes low when Clock0 driver is not toggling / has a fault
Clock1 Ready	Pin 3	Pin 3	Goes low when Clock1 driver is not toggling / has a fault
Clock2 Ready	Pin 23	Pin 23	Goes low when Clock2 driver is not toggling / has a fault
Clock3 Ready	Pin 24	Pin 24	Goes low when Clock3 driver is not toggling / has a fault
Clock01 Ready	Pin 6	-	Goes low when Clock0 or Clock1 driver are not toggling / have a fault
Clock23 Ready	Pin 7	-	Goes low when Clock2 or Clock3 driver are not toggling / have a fault
VDDO0 Good	Pin 2	Pin 2	Goes low when VDDO0 supply is below NVM-configured threshold
VDDO1 Good	Pin 3	Pin 3	Goes low when VDDO1 supply is below NVM-configured threshold
VDDO2 Good	Pin 23	Pin 23	Goes low when VDDO2 supply is below NVM-configured threshold
VDDO3 Good	Pin 24	Pin 24	Goes low when VDDO3 supply is below NVM-configured threshold
All Clocks Ready	Pin 2 / 3 / 4 / 6 / 7 / 23 / 24	Pin 2 / 3 / 23 / 24	Goes low when any enabled clock output is not toggling / has a fault
Alarm_B	Pin 2 / 3 / 4 / 6 / 7 / 23 / 24	Pin 2 / 3 / 23 / 24	Goes low when any fault is triggered
ISP_Burn_Success	Pin 4	(Access via register read)	Asserted when in-system NVM burn is successful
VDDO01 Good	Pin 6	-	Goes low when VDDO0 or VDDO1 are below NVM-configured thresholds
VDDO23 Good	Pin 7	-	Goes low when VDDO2 or VDDO3 are below NVM-configured thresholds
Die Temperature Out of Range	Accessible via register reads only		Asserted if die temperature is outside NVM-configured range. Available via direct register access through I2C/SPI

General Purpose Inputs

Table 2. User Configurable Input Signals³

Input Function	Available on GPIO Pin (Parts without I2C/SPI)	Available on GPIO Pin (Parts with I2C)	Available on GPIO Pin (Parts with SPI)	Function
SSEN / $\overline{\text{SSEN}}$	Pin 1 / 3 / 4 / 8	Pin 1 / 3 / 4	Pin 1 / 3	Spread Spectrum enabled on all outputs (configurable active high or low)
OE0 / $\overline{\text{OE0}}$	Pin 2 / 3	Pin 2 / 3	Pin 2 / 3	Enable Output 0 (configurable active high or low)
OE1 / $\overline{\text{OE1}}$	Pin 2 / 3	Pin 2 / 3	Pin 2 / 3	Enable Output 1 (configurable active high or low)
OE2 / $\overline{\text{OE2}}$	Pin 1 / 6 / 7	Pin 1 / 6 / 7	Pin 1 / 6	Enable Output 2 (configurable active high or low)
OE3 / $\overline{\text{OE3}}$	Pin 1 / 6 / 7	Pin 1 / 6 / 7	Pin 1 / 6	Enable Output 3 (configurable active high or low)
OE_all / $\overline{\text{OE_all}}$	Pin 2 / 7	Pin 2 / 7	Pin 2	Enable all Outputs (configurable active high or low)
FS0	Pin 9 / 23	Pin 23	Pin 23	Frequency Select 0
FS1	Pin 8 / 24	Pin 24	Pin 24	Frequency Select 1

Note:

3. The I2C and SPI pins can be reconfigured, in factory, as GPIO pins. Such parts (without the I2C or SPI interface) can be ordered directly only from SiTime.

SiT91281 Low Jitter, 4-Output, AEC-Q100 MEMS Clock Generator**Electrical Characteristics**

All Min and Max limits in the Electrical Characteristics tables are specified over operating temperature and rated operating voltage with standard output termination shown in the termination diagrams. Typical values are at 25°C and nominal supply voltage. See [Test Circuit Diagrams](#) for the test setups used with each signaling type.

Table 3. Electrical Characteristics – Common to All Output Signaling Types

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Frequency Range						
Output Frequency Range	f			700	MHz	Differential clock outputs LVDS, LVPECL, FlexSwing
	f			350	MHz	Differential clock outputs HCSL LPHCSL
	f			220	MHz	Single-ended (LVCMOS) clock outputs
Frequency Stability						
Frequency Stability Contact SiTime for ±30 ppm		–	–	±20	ppm	Inclusive of initial tolerance, operating temperature range -40°C to 105°C, rated power supply voltage, load variation of 2 pF ± 10%, and 10 years aging at 85°C
		–	–	±50	ppm	Inclusive of initial tolerance, operating temperature range -40°C to 125°C, rated power supply voltage, load variation of 2 pF ± 10%, and 10 years aging at 85°C
Temperature Range						
Operating Temperature Range	T _{use}	-40	–	+105	°C	Automotive Grade 2 Temperature Range
		-40	–	+125	°C	Automotive Grade 1 Temperature Range
Supply Voltage						
Supply Voltage		1.71	1.80	1.89	V	
		2.25	2.50	2.75	V	
		2.97	3.30	3.63	V	
Core Current						
Core Current	I _{dd}	-	-	55	mA	Total current consumed on the VDD and VDDA power domains
Input Characteristics						
Input Voltage High	V _{IH}	70%	–	–	V _{dd}	Logic High function for all input pins
Input Voltage Low	V _{IL}	–	–	30%	V _{dd}	Logic High function for all input pins
Output Characteristics						
Duty Cycle	DC	45	–	55	%	See Figure 13 for waveform
Startup, OE and SE Timing						
Startup Time	T _{start}	–	1.2	2	ms	Measured from the time V _{dd} reaches its rated minimum value
Output Enable Time	T _{oe}	–	–	600+1 clock cycles	ns	For all signaling types. Measured from the time OE pin toggles to enable logic level to the time clock pins reach 90% of final swing. See Figure 19 for waveform
Output Disable Time	T _{od}	–	–	600+1 clock cycles	ns	Measured from the time OE pin toggles to disable logic level to the last clock edge. See Figure 20 for waveform
Jitter and Phase Noise, measured at f = 156.25 MHz						
RMS Phase Jitter (“4-16A”)	T _{phj}	–	115	–	fs	“4-16A” 4 MHz to 16 MHz offset frequency integration bandwidth with aliasing
RMS Phase Jitter (random)	T _{phj}	–	150	200	fs	12 kHz to 20 MHz offset frequency integration bandwidth
Spurious Phase Noise	T _{spn}	–	–	-95	dBc	12 kHz to 20 MHz offset frequency range
RMS Period Jitter ^[4]	T _{jitt_per}	–	0.5	0.6	ps	Measured based on 10K cycle
Peak Cycle-to-cycle Jitter ^[4]	T _{jitt_cc}	–	3.5	6.2	ps	Measured based on 1K cycle
Synchronization and Timing						
Output Skew	t _{SK,B}			150	ps	
Spread-Spectrum Generation						
Center Spread		-0.125		+0.125	%	
		-0.25		+0.25	%	
		-0.5		+0.5	%	
Down Spread		-0.25		0	%	
		-0.5		0	%	
Modulation Rate		31.05	31.25	31.45	kHz	

Note:

4. Measured according to JESD65B using Keysight DSAX91604A Oscilloscope.

SiT91281 Low Jitter, 4-Output, AEC-Q100 MEMS Clock Generator**Table 4. Electrical Characteristics – LVPECL** | See [Figure 2](#) and [Figure 3](#) for test setups. Current consumption only accounts for VDDO and output driver stage. Measurements are with VDDO = 3.3 V or 2.5 V.

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Current Consumption, f = 156.25 MHz						
Current Consumption, Output Enabled without Termination	Idd_oe_nt	–	–	25	mA	Excluding load termination current VDDO = 3.3 V
Current Consumption, Output Disabled without Termination	Idd_od_nt	–	–	13	mA	Excluding load termination current VDDO = 3.3 V, outputs are Hi-Z
Current Consumption, Output Enabled with Termination 1	Idd_oe_wt1	–	–	38	mA	Including load termination current as shown in Figure 24 for Vdd=3.3 V $\pm 10\%$ and R3 = 220 Ohms
		–	–	36	mA	Including load termination current as shown in Figure 24 for Vdd=2.5 V $\pm 10\%$ and R3 = 220 Ohms
Current Consumption Output Disabled with Termination 1	Idd_od_wt1	–	–	26	mA	Including load termination current as shown in Figure 24 for Vdd=3.3 V $\pm 10\%$ and R3 = 220 Ohms. Driver output is held at last clock output levels
		–	–	24	mA	Including load termination current as shown in Figure 24 for Vdd=2.5 V $\pm 10\%$ and R3 = 220 Ohms. Driver output is held at last clock output levels
Current Consumption, Output Enabled with Termination 2	Idd_oe_wt2	–	–	53	mA	Including load termination current. VDDO = 3.3 V. See Figure 25 for termination
Current Consumption, Output Disabled with Termination 2	Idd_od_wt2	–	–	41	mA	Including load termination current. See Figure 25 for termination. Driver output is held at last clock output levels
Output Characteristics						
Output High Voltage	VOH	Vdd-1.075	Vdd-0.95	Vdd-0.86	V	See Figure 12 for waveform
Output Low Voltage	VOL	Vdd-1.84	Vdd-1.7	Vdd-1.62	V	See Figure 12 for waveform
Output Differential Voltage Swing	V_Swing	1.4	–	1.8	V	See Figure 13 for waveform
Rise/Fall Time	Tr, Tf	–	210	300	ps	20% to 80%. See Figure 13 for waveform
Differential Asymmetry, peak-peak	V_da	–	–	85	mV	See Figure 15 for waveform
Differential Skew, peak	V_ds	–	–	± 25	ps	See Figure 16 for waveform
Overshoot Voltage, peak	V_ov	–	–	12	%	Measured as percent of V_Swing See Figure 17 for waveform
Power Supply Noise Immunity (VDDO)						
Power Supply-Induced Jitter Sensitivity	PSJS	–	–	10	fs/mV	Power supply ripple from 10 kHz to 20 MHz
		–	–	TBD	fs/mV	Power supply ripple from 10 kHz to 20 MHz Using RC power supply filter as shown in Figure 2
Power Supply-Induced Phase Noise	PSPN	–	–	-85	dBc	50 mV peak-peak ripple on VDD
		–	–	TBD	dBc	50 mV peak-peak ripple on VDD Using RC power supply filter as shown in Figure 2

SiT91281 Low Jitter, 4-Output, AEC-Q100 MEMS Clock Generator**Table 5. Electrical Characteristics – FlexSwing** | See [Figure 4](#) and [Figure 5](#) for test setups. Current consumption only accounts for VDDO and output driver stage.

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Current Consumption						
Current Consumption, Output Enabled without Termination	Idd_oe_nt	–	–	25	mA	Excluding load termination current
Current Consumption, Output Disabled without Termination	Idd_od_nt	–	–	13	mA	Excluding load termination current
Current Consumption, Output Enabled with Termination	Idd_oe_wt	–	–	35	mA	Including load termination current, for FlexSwing code “ER”. See Figure 24 for Vdd = 3.3 V ±10% and R3 = 220 Ohms
		–	–	35	mA	Including load termination current, for FlexSwing code “ER”. See Figure 24 for Vdd = 2.5 V ±10%, and R3 = 220 Ohms
Current Consumption Output Disabled with Termination	Idd_od_wt	–	–	23	mA	Including load termination current, for FlexSwing code “ER”. See Figure 24 for Vdd = 3.3 V ±10% and R3 = 220 Ohms. Driver output is held at last clock output levels
		–	–	23	mA	Including load termination current, for FlexSwing code “ER”. See Figure 24 for Vdd = 2.5 V ±10%, and R3 = 220 Ohms. Driver output is held at last clock output levels
Output Characteristics						
Output High Voltage	VOH	VHn -0.13	VHn	VHn +0.1	V	See Figure 12 for waveform; Refer to Table 10 or Table 11 order codes for nominal VOH (i.e. VHn) values
Output Low Voltage	VOL	VLn -0.13	VLn	VLn +0.12	V	See Figure 12 for waveform; Refer to Table 10 or Table 11 order codes for nominal VOL (i.e. VLn) values
Output Differential Voltage Swing	V_Swing	-0.2	2*(VHn-VLn)	+0.2	V	See Figure 13 for waveform
Rise/Fall Time	Tr, Tf	–	170	300	ps	20% to 80%. See Figure 13 for waveform
Differential Asymmetry, peak-peak	V_da	–	–	100	mV	See Figure 15 for waveform
Differential Skew, peak	V_ds	–	–	±25	ps	See Figure 16 for waveform
Overshoot Voltage, peak	V_ov	–	–	12	%	Measured as percent of V_Swing. See Figure 17 for waveform
Power Supply Noise Immunity (VDDO)						
Power Supply-Induced Jitter Sensitivity	PSJS	–	–	10	fs/mV	Power supply ripple from 10 kHz to 20 MHz. For FlexSwing code “ER”
		–	–	TBD	fs/mV	Power supply ripple from 10 kHz to 20 MHz. For FlexSwing code “ER”. Using RC power supply filter shown in Figure 4
Power Supply-Induced Phase Noise	PSPN	–	–	-85	dBc	50 mV peak-peak ripple on VDDO. For FlexSwing code “ER”
		–	–	TBD	dBc	50 mV peak-peak ripple on VDDO. For FlexSwing code “ER”. Using RC power supply filter shown in Figure 4

Table 6. Electrical Characteristics – LVDS | See [Figure 6](#) and [Figure 7](#) for test setups. Current consumption only accounts for VDDO and output driver stage.

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Current Consumption						
Current Consumption, Output Enabled without Termination	Idd_oe_nt	–		25	mA	Excluding load termination current
Current Consumption, Output Disabled without Termination	Idd_od_nt	–		13	mA	Excluding load termination current
Current Consumption, Output Enabled with Termination	Idd_oe_wt	–		29	mA	Including load termination current. See Figure 28 for termination
Current Consumption Output Disabled with Termination	Idd_od_wt	–		17	mA	Including load termination current. See Figure 28 for termination. Driver output is held at last clock output levels
Output Characteristics						
Differential Output Voltage	VOD	250	360	450	mV	See Figure 14 for waveform
Delta VOD	ΔVOD	–	–	50	mV	See Figure 14 for waveform
Offset Voltage	VOS	1.125	1.25	1.375	V	See Figure 14 for waveform. VDDO = 3.3 V and 2.5 V
		1.0	–	1.05	V	See Figure 14 for waveform VDDO = 1.8 V
Delta VOS	ΔVOS	–	–	50	mV	See Figure 14 for waveform
Rise/Fall Time	Tr, Tf	–	–	250	ps	Measured 20% to 80% using Figure 28 for termination. See Figure 13 for waveform
Differential Asymmetry, peak-peak	V_da	–	–	50	mV	See Figure 15 for waveform
Differential Skew, peak	V_ds	–	–	±50	ps	See Figure 16 for waveform
Overshoot Voltage, peak	V_ov	–	–	10	%	Measured as percent of VOD. See Figure 18 for waveform
Power Supply Noise Immunity (VDDO)						
Power Supply-Induced Jitter Sensitivity	PSJS	–	–	10	fs/mV	Power supply ripple from 10 kHz to 20 MHz
	PSJS	–	–	TBD	fs/mV	Power supply ripple from 10 kHz to 20 MHz. Using RC power supply filter as shown in Figure 6
Power Supply-Induced Phase Noise	PSPN	–	–	-85	dBc	50 mV peak-peak ripple on VDDO
	PSPN	–	–	TBD	dBc	50 mV peak-peak ripple on VDDO. Using RC power supply filter as shown in Figure 6

Table 7. Electrical Characteristics – HCSL | See [Figure 8](#) and [Figure 9](#) for test setups. Current consumption only accounts for VDDO and output driver stage.

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Current Consumption						
Current Consumption, Output Enabled without Termination	Idd_oe_nt	–	–	25	mA	Excluding load termination current
Current Consumption, Output Disabled without Termination	Idd_od_nt	–	–	13	mA	Excluding load termination current
Output Characteristics						
Output High Voltage	VOH	0.60	0.7	0.95	V	See Figure 12 for waveform
Output Low Voltage	VOL	-0.1	0	0.1	V	See Figure 12 for waveform
Output Differential Voltage Swing	V_Swing	1.1	1.4	1.6	V	See Figure 13 for waveform
Rise/Fall Time	Tr, Tf	–	170	300	ps	Measured 20% to 80%. See Figure 13 for waveform
Differential Asymmetry, peak-peak	V_da	–	–	65	mV	See Figure 15 for waveform
Differential Skew, peak	V_ds	–	–	±25	ps	See Figure 16 for waveform
Overshoot Voltage, peak	V_ov	–	–	10	%	Measured as percent of V_Swing. See Figure 17 for waveform
Power Supply Noise Immunity (VDDO)						
Power Supply-Induced Jitter Sensitivity	PSJS	–	–	10	fs/mV	Power supply ripple from 10 kHz to 20 MHz
		–	–	TBD	fs/mV	Power supply ripple from 10 kHz to 20 MHz. Using RC power supply filter as shown in Figure 8
Power Supply-Induced Phase Noise	PSPN	–	–	-85	dBc	50 mV peak-peak ripple on VDDO
		–	–	TBD	dBc	50 mV peak-peak ripple on VDDO. Using RC power supply filter as shown in Figure 8

SiT91281 Low Jitter, 4-Output, AEC-Q100 MEMS Clock Generator**Table 8. Electrical Characteristics – Low-Power HCSL** | See [Figure 10](#) and [Figure 11](#) for test setups. Current consumption only accounts for VDDO and output driver stage.

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Current Consumption						
Current Consumption, Output Enabled without Termination	Idd_oe_nt	–	–	25	mA	Excluding load termination current
Current Consumption, Output Disabled without Termination	Idd_od_nt	–	–	13	mA	Excluding load termination current
Output Characteristics						
Output High Voltage	VOH	–	–	1.1	V	See Figure 12 for waveform
Output Low Voltage	VOL	-0.1	0	0.1	V	See Figure 12 for waveform
Output Differential Voltage Swing	V_Swing	1.4	1.83	2.0	V	See Figure 13 for waveform
Rise/Fall Time	Tr, Tf	–	–	80	ps	Measured 20% to 80%. See Figure 13 for waveform
Differential Asymmetry, peak-peak	V_da	–	–	85	mV	See Figure 15 for waveform
Differential Skew, peak	V_ds	–	–	±30	ps	See Figure 16 for waveform
Overshoot Voltage, peak	V_ov	–	–	10	%	Measured as percent of V_Swing. See Figure 17 for waveform
Power Supply Noise Immunity (VDDO)						
Power Supply-Induced Jitter Sensitivity	PSJS	–	–	10	fs/mV	Power supply ripple from 10 kHz to 20 MHz
		–	–	TBD	fs/mV	Power supply ripple from 10 kHz to 20 MHz. Using RC power supply filter as shown in Figure 10
Power Supply-Induced Phase Noise	PSPN	–	–	-85	dBc	50 mV peak-peak ripple on VDDO
		–	–	TBD	dBc	50 mV peak-peak ripple on VDDO. Using RC power supply filter as shown in Figure 10

SiT91281 Low Jitter, 4-Output, AEC-Q100 MEMS Clock Generator**Table 9. Electrical Characteristics – Low-Voltage CMOS** | Current consumption only accounts for VDDO and output driver stage.

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Current Consumption						
Current Consumption, Output Enabled	Idd_oe	–	–	14	mA	VDDO = 3.3 V, output frequency 20 MHz, load = 8 pF
Current Consumption, Output Disabled	Idd_od	–	–	12	mA	VDDO = 3.3 V
Output Characteristics (Standard LVCMOS)						
Output High Voltage	VOH	90%	–	–	VDDO	IOH = -4 mA, VDDO = 3.3 V
Output Low Voltage	VOL	–	–	10%	VDDO	IOL = 4 mA, VDDO = 3.3 V
Rise/Fall Time	Tr, Tf	–	0.4	0.6	ns	Measured 20% to 80%, output frequency 20 MHz, load = 8 pF. SiT91281 has programmable options for rise-time & fall-time
Duty Cycle		45	–	55	%	Measured in percentage of clock period
Overshoot Voltage, peak	V_ov	–	–	10	%	Measured as percent of difference between VOH and VOL
Output Characteristics (Regulated LVCMOS)						
Output High Voltage Regulated Range	VDDOreg	0.9	–	VDDO-0.3	V	Regulated VOH can be programmed with up to 20 steps
Output High Voltage Regulated Range	VOH	90%	–	–	VDDOreg	IOH = -4 mA, VDDO = 3.3 V
Output Low Voltage	VOL	–	–	10%	VDDreg	IOL = 4 mA, VDDO = 3.3 V
Rise/Fall Time	Tr, Tf	–	0.4	0.6	ns	Measured 20% to 80%, output frequency 20 MHz, load = 8 pF. SiT91281 has programmable options for rise-time & fall-time
Overshoot Voltage, peak	V_ov	–	–	10	%	Measured as percent of difference between VOH and VOL
Power Supply Noise Immunity (VDDO)						
Power Supply-Induced Jitter Sensitivity	PSJS	–	–	20	fs/mV	Power supply ripple from 10 kHz to 20 MHz
Power Supply-Induced Phase Noise	PSPN	–	–	TBD	dBc	50 mV peak-peak ripple on VDDO

FlexSwing Configurations

A FlexSwing output-driver performs like LVPECL and additionally provides independent control of voltage swing and DC offset voltage levels. This simplifies interfacing with chipsets having non-standard input voltage requirements

and can eliminate all external source-bias resistors. FlexSwing supports power supply voltages from 1.71 V to 3.63 V, and the programmable VOH and VOL levels may be referenced to the voltage on either VDD or GND pins.

Table 10. FlexSwing 2-digit Codes specifying V_{Hn} and V_{Ln} referenced to voltage on VDD pin^[6]

[illegible]

Note:

5. Please [contact SiTime](#).
6. Table based on Y-Bias Termination with $R3 = 220$. See [Figure 24](#).

The above table identifies supported combinations of nominal VOH (i.e. V_{Hn}) and nominal VOL (i.e. V_{Ln}) in colored boxes. The two-character code in each box corresponds to the V_{Hn} and V_{Ln} codes specified in the 2nd column and 2nd row in the table, respectively. The number in each box indicates the nominal differential swing (i.e. V_{Hn} – V_{Ln}).

For example, order code “FS” selects V_{Hn} code “F” (i.e. V_{dd}-1.144 V) and V_{Ln} code “S” (i.e. V_{dd}-1.530 V) corresponding to a V_{Swing} of 0.845 V peak-peak, which may be used for supply voltages of 2.5 V \pm 10%, 3.3 V \pm 10% or (2.25 V to 3.63 V). Alternatively, an order code of “GS” corresponds to a V_{Hn} code “G” (i.e. V_{dd}-1.193 V) and a V_{Ln} order code “S” (e.g. V_{dd}-1.530 V) corresponding to a V_{Swing} of 0.760 V peak-peak, which may be used for a supply voltage of 3.3 V \pm 10%.

Table 11. FlexSwing 2-digit Codes specifying VHn and VLn referenced to voltage on GND pin

Order Code V_Swing (V)		C	D	E	F	G	H	J	K	L	M	N	P	Q	R	S	T	U	V	W	X	Y
		0.45V	0.49V	0.54V	0.59V	0.64V	0.69V	0.74V	0.79V	0.84V	0.89V	0.94V	0.99V	1.03V	1.08V	1.16V	1.23V	1.3V	1.38V	1.45V	1.53V	1.6V
VHn	A																		AV	AW	AX	AY
	B																		1.94	1.86	1.69	1.61
	C																		1.86	1.77	1.61	1.52
	D																		1.94	1.77	1.69	1.61
	E																		1.86	1.77	1.61	1.52
	F																		1.94	1.77	1.69	1.61
	G																		1.86	1.77	1.61	1.52
	H																		1.94	1.77	1.69	1.61
	J																		1.86	1.77	1.61	1.52
	K																		1.94	1.77	1.69	1.61
	L																		1.86	1.77	1.61	1.52
	M																		1.94	1.77	1.69	1.61
	N																		1.86	1.77	1.61	1.52
	P																		1.94	1.77	1.69	1.61
	Q																		1.86	1.77	1.61	1.52
	R																		1.94	1.77	1.69	1.61
	S																		1.86	1.77	1.61	1.52
	T																		1.94	1.77	1.69	1.61
	U																		1.86	1.77	1.61	1.52
	V																		1.94	1.77	1.69	1.61
	W																		1.86	1.77	1.61	1.52
	X																		1.94	1.77	1.69	1.61
	Y																		1.86	1.77	1.61	1.52
	Z																		1.94	1.77	1.69	1.61
	1																		1.86	1.77	1.61	1.52
	2																		1.94	1.77	1.69	1.61
	3																		1.86	1.77	1.61	1.52

Note:

7. Please [contact SiTime](#).

Test Circuit Diagrams

A 1.5 pF capacitive load is used at each differential output. Because of the additive input capacitance of the active probe used with the oscilloscope, the output characteristics for all signal types are measured with a total of 2 pF capacitive load.

Test Setups for LVPECL Measurements

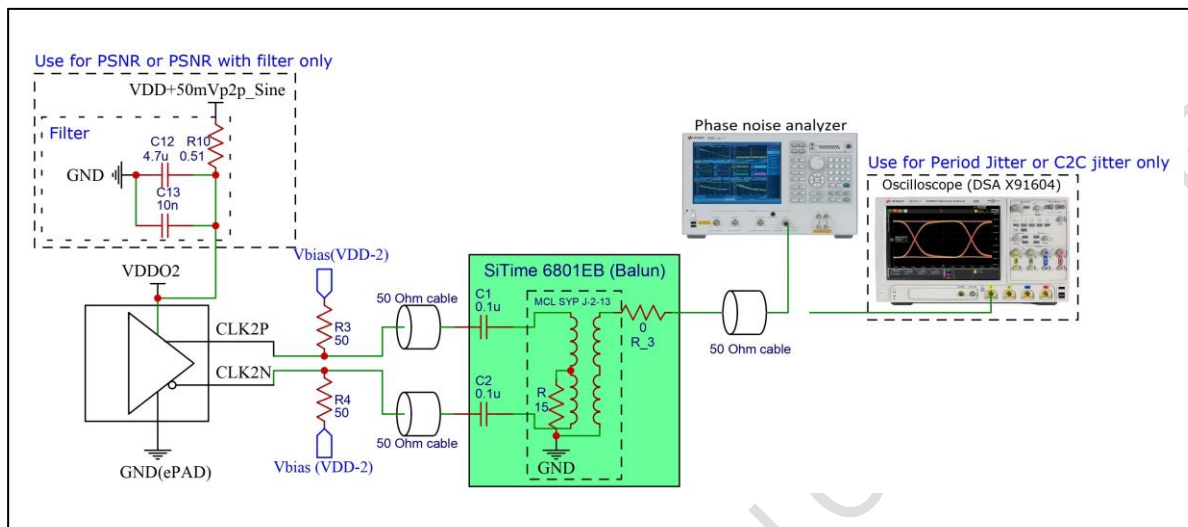


Figure 2. Test setup to measure LVPECL Phase Noise, Period Jitter, Cycle-to-Cycle Jitter, and Power Supply-Induced Phase Noise (PSPN) without filter added^[8]

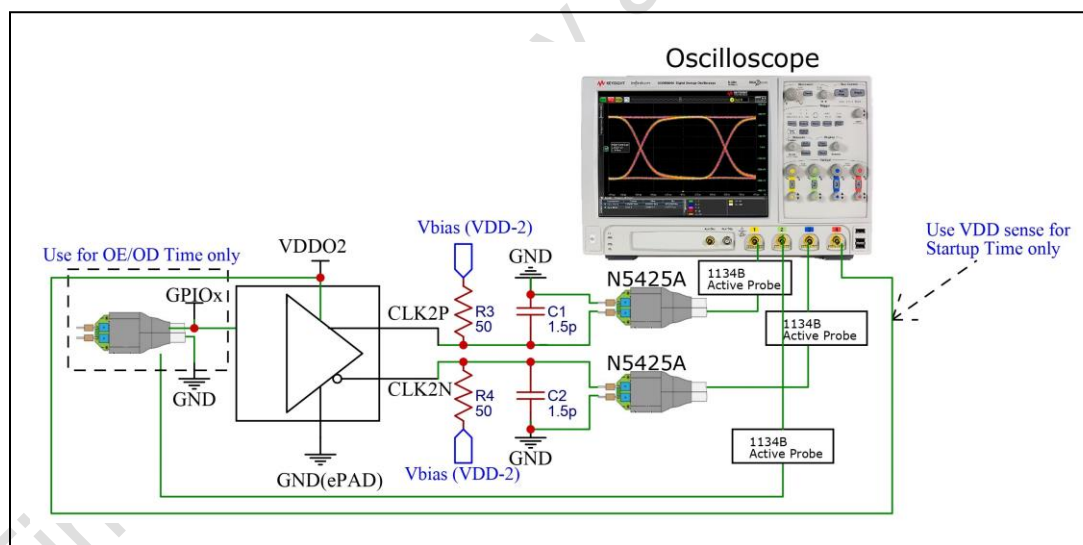


Figure 3. Test setup to measure LVPECL Waveform Characteristics, Current Consumption (with Termination 2)^[9], Output Enable/Disable Time, and Startup Time

Notes:

8. See [Figure 4](#) for the test setup to measure LVPECL Power Supply-Induced Phase Noise (PSPN) with filter added.
9. See [Figure 5](#) for the test setup to measure LVPECL Current Consumption with Termination 1 or without Termination.

Test Circuit Diagrams (continued)

Test Setups for FlexSwing Measurements^[10]

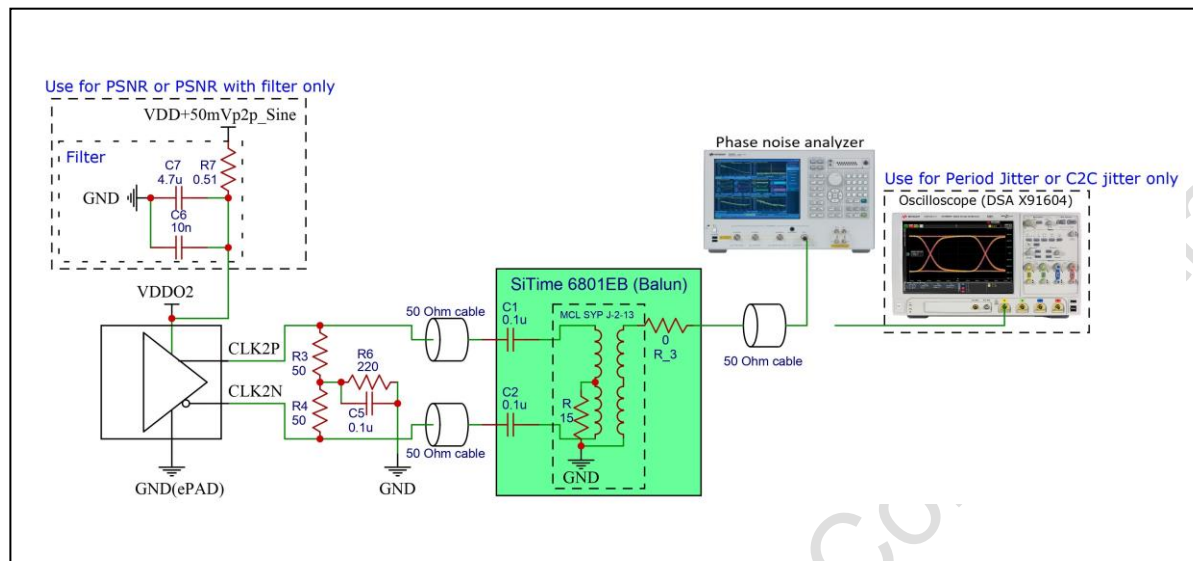


Figure 4. Test setup to measure FlexSwing Phase Noise, Period Jitter, Cycle-to-Cycle Jitter, and Power Supply-Induced Phase Noise (PSPN) with and without filter added^[11]

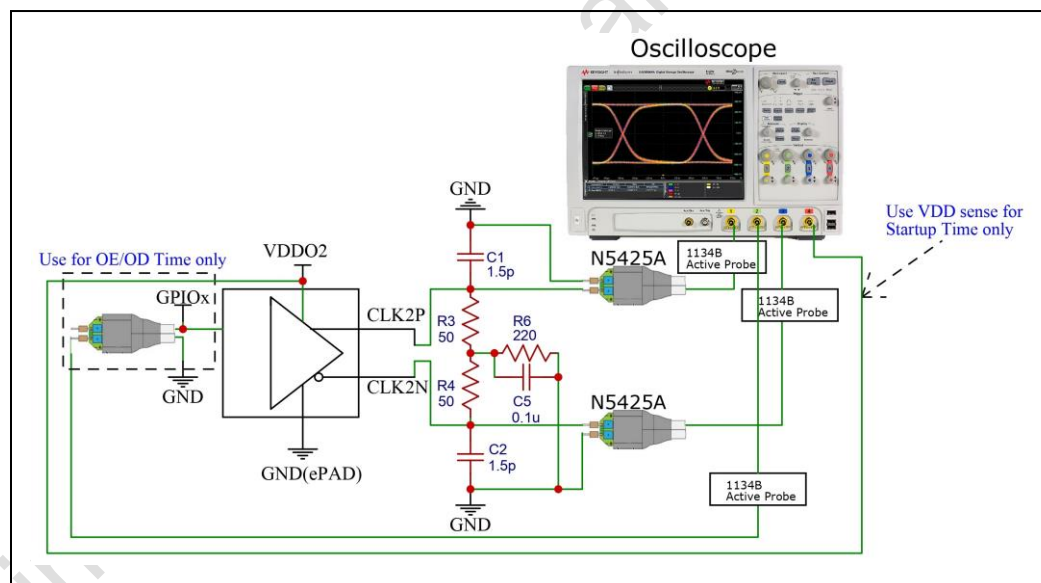


Figure 5. Test setup to measure FlexSwing Waveform Characteristics, Current Consumption^[12], Output Enable/Disable Time, and Startup Time

Note:

10. The same test circuits are used for FlexSwing referenced to VDD and FlexSwing referenced to GND.
11. Test setup is also used to measure LVPECL Power Supply-Induced Phase Noise (PSPN) with filter added.
12. Test setup is also used to measure LVPECL Current Consumption with Termination 1 or without Termination.

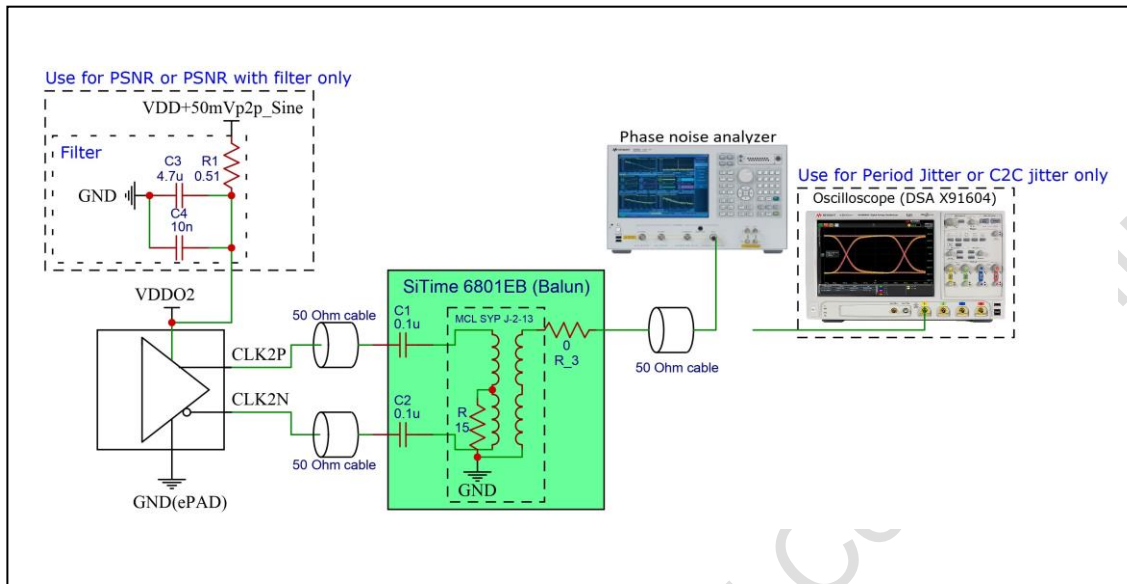
Test Circuit Diagrams (continued)**Test Setups for LVDS Measurements**

Figure 6. Test setup to measure LVDS Phase Noise, Period Jitter, Cycle-to-Cycle Jitter, and Power Supply-Induced Phase Noise (PSPN) with and without filter added

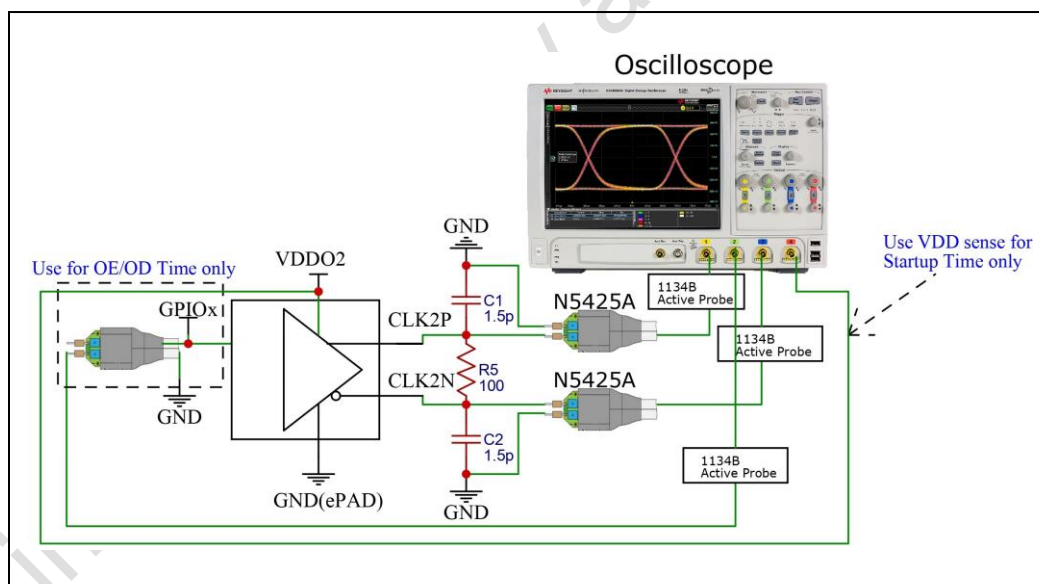


Figure 7. Test setup to measure LVDS Waveform Characteristics, Current Consumption, Output Enable/Disable Time, and Startup Time

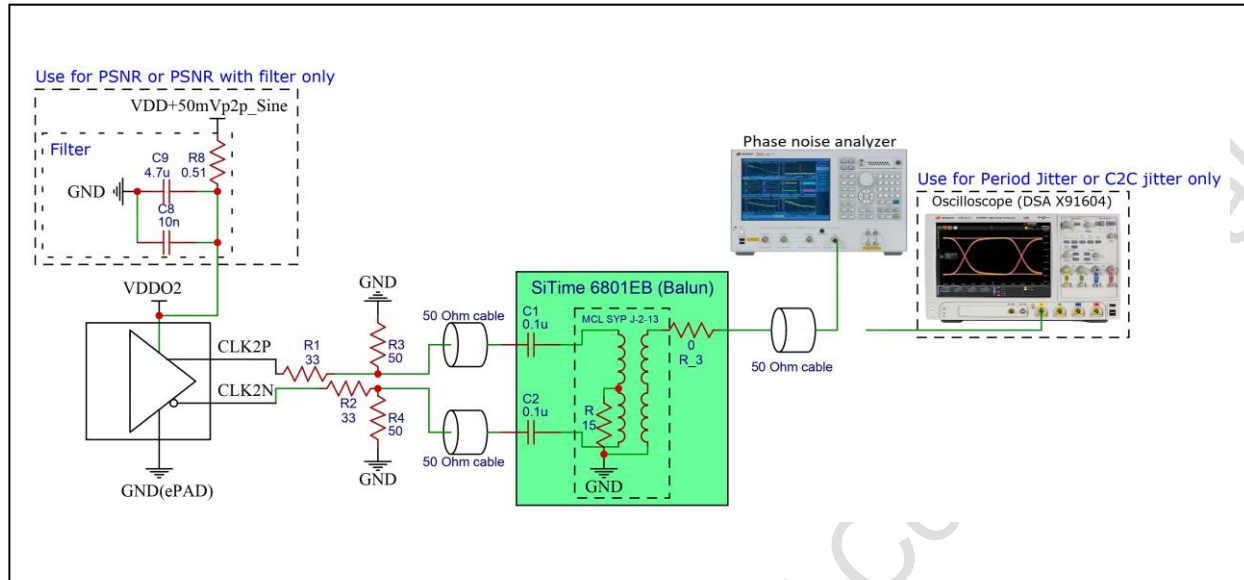
Test Circuit Diagrams (continued)**Test Setups for HCSL Measurements**

Figure 8. Test setup to measure HCSL Phase Noise, Period Jitter, Cycle-to-Cycle Jitter, and Power Supply-Induced Phase Noise (PSPN) with and without filter added

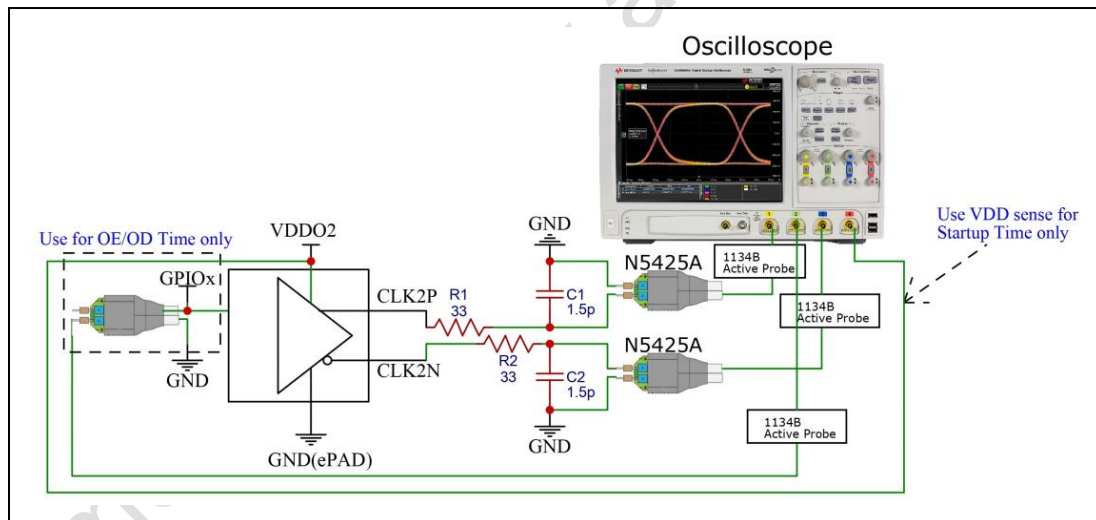


Figure 9. Test setup to measure HCSL Waveform Characteristics, Current Consumption, Output Enable/Disable Time, and Startup Time

Test Circuit Diagrams (continued)

Test Setups for Low-Power HCSL Measurements

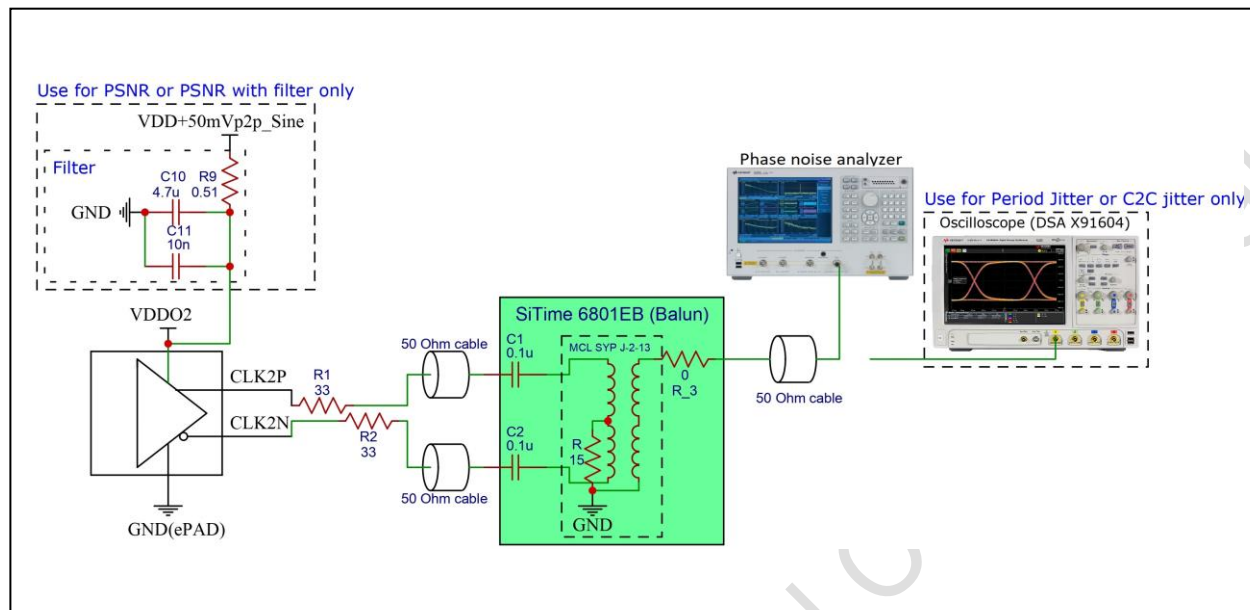


Figure 10. Test setup to measure Low-Power HCSL Phase Noise, Period Jitter, Cycle-to-Cycle Jitter, and Power Supply-Induced Phase Noise (PSPN) with and without filter added

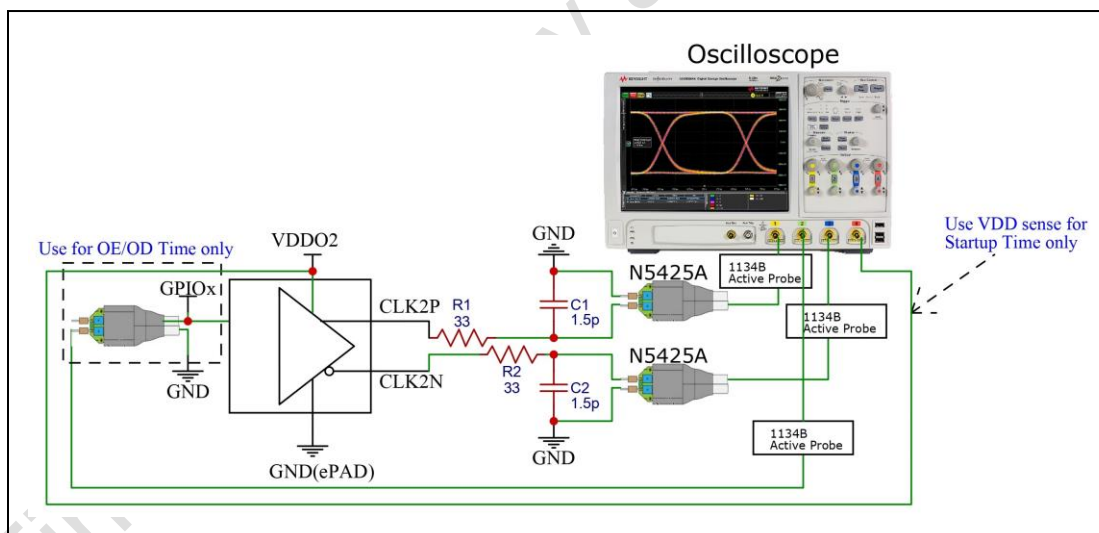


Figure 11. Test setup to measure Low-Power HCSL Waveform Characteristics, Current Consumption, Output Enable/Disable Time, and Startup Time

Waveform Diagrams

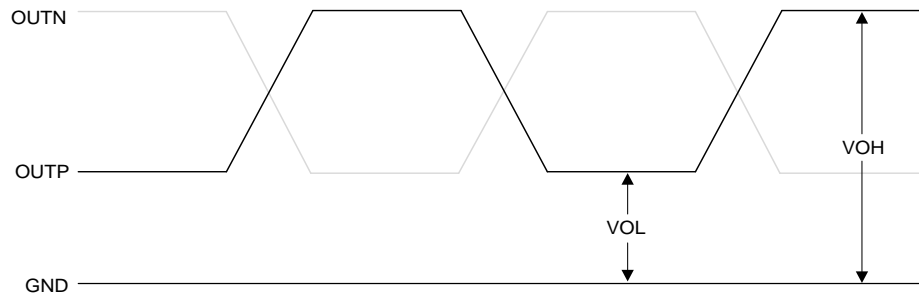


Figure 12. LVPECL, HCSL, Low-Power HCSL, and FlexSwing Voltage Levels per Differential Pin

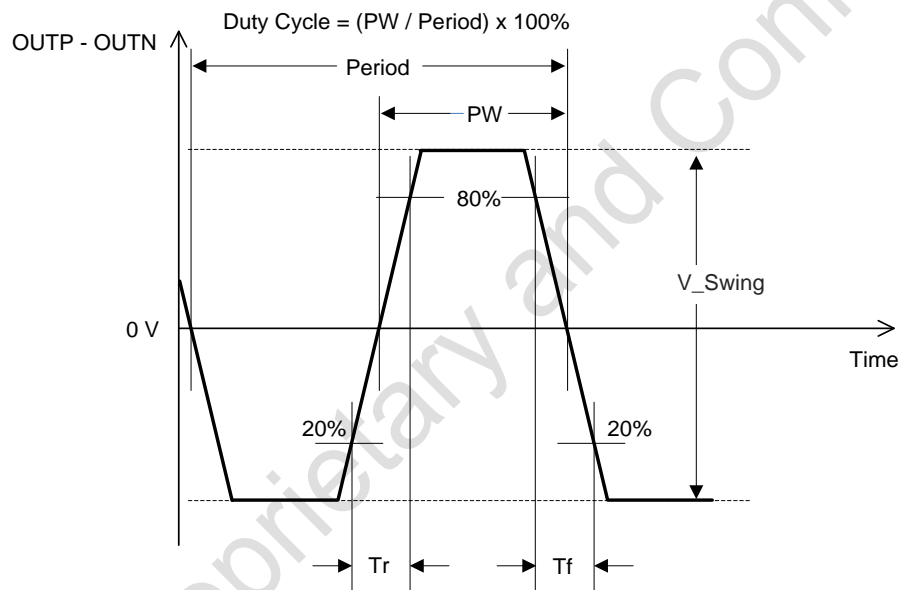


Figure 13. LVPECL, LVDS, HCSL, Low-Power HCSL, and FlexSwing Voltage Levels Across Differential Pair

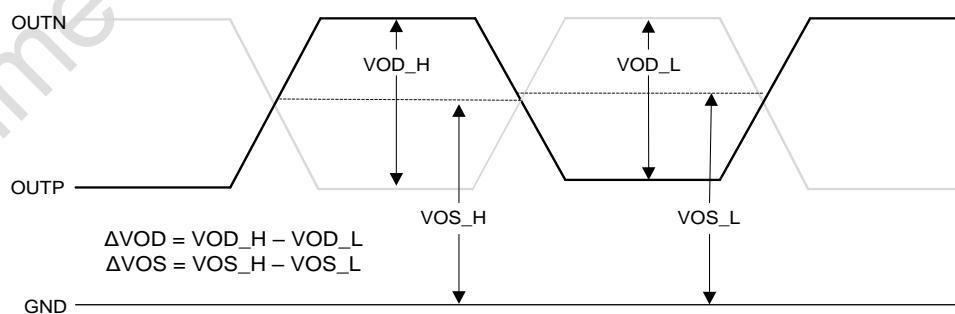


Figure 14. LVDS Voltage Levels per Differential Pin

Waveform Diagrams (continued)

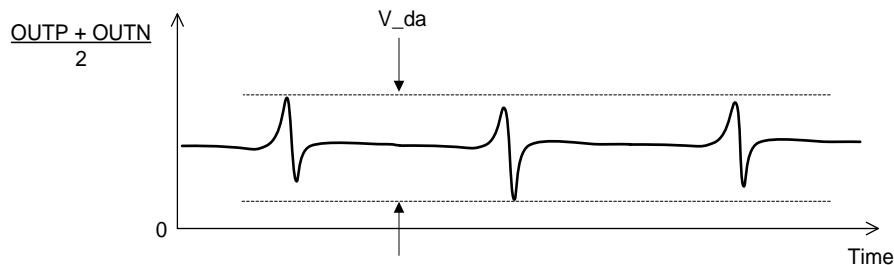


Figure 15. Differential Asymmetry (V_{da})

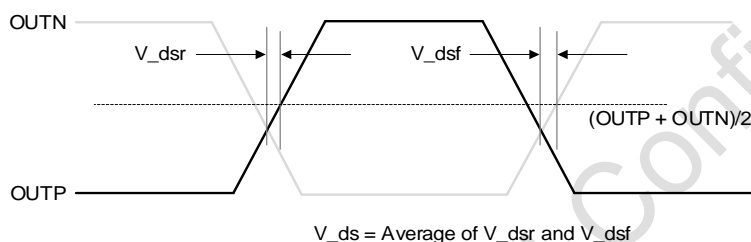


Figure 16. Differential Skew (V_{ds}) is measured as the Time between the Average Voltage Level and Crossing Voltage

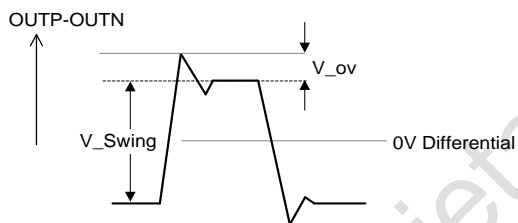


Figure 17. Overshoot Voltage (V_{ov}) for LVPECL, FlexSwing, HCSL, Low-power HCSL

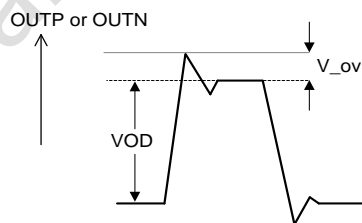


Figure 18. Overshoot Voltage (V_{ov}) for LVDS Output

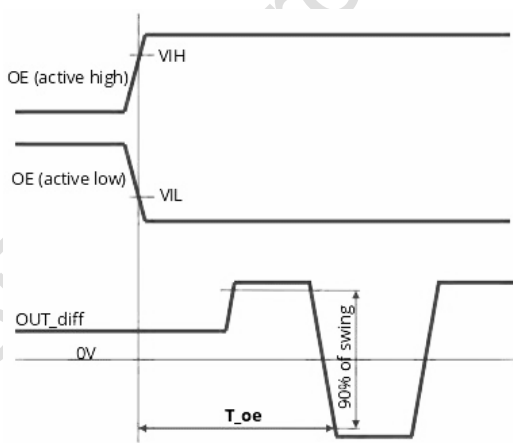


Figure 19. OE Pin Enable Timing (T_{oe})

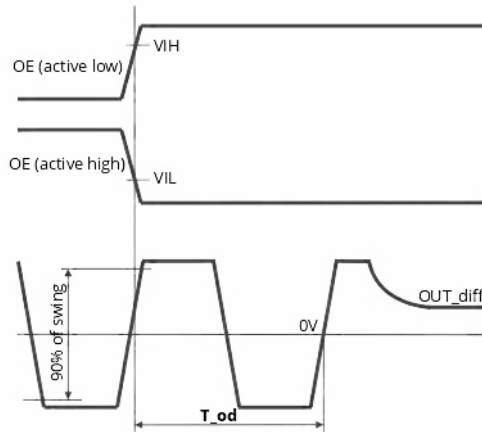


Figure 20. OE Pin Disable Timing (T_{od})

Termination Diagrams

LVPECL and FlexSwing Termination

The SiT91281 FlexSwing output drivers support low power without sacrificing signal integrity via simple terminations as shown in Figure 22 and Figure 24, compared to traditional LVPECL drivers. The FlexSwing and LVPECL outputs are

voltage-mode drivers. Use the table and figures below to select a termination circuit for the desired supply voltage. The table also provides LVPECL current consumption (I_{load}) into the load termination.

Table 12. Termination Options for LVPECL and FlexSwing Signaling

Signaling	Termination Options					
	Figure 21	Figure 22	Figure 23	Figure 24	Figure 25	Figure 26
LVPECL referenced to Vdd	OK to use $I_{load} = 40$ mA with 100 Ω near-end bias resistor	Do Not Use	OK to use $I_{load} = 28$ mA	OK to use	OK to use $I_{load} = 28$ mA	Do Not Use
FlexSwing referenced to Vdd	OK to use ^[13]	OK to use (see Figure 22 for frequency ranges and voltage swings)	OK to use ^[13]	OK to use	OK to use	Do Not Use
FlexSwing referenced to Gnd			Do Not Use	OK to use	Do Not Use	Do Not Use
			Do Not Use	OK to use	Do Not Use	OK to use

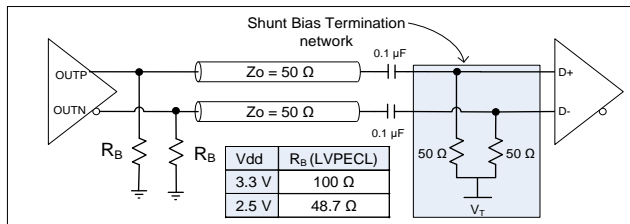


Figure 21. Recommended LVPECL and FlexSwing^[14] Termination when AC-coupled

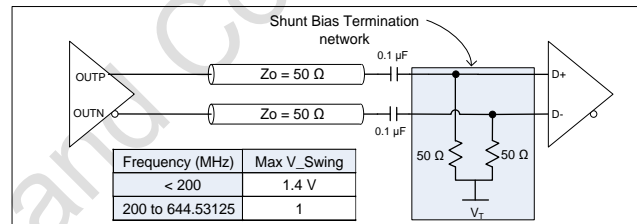


Figure 22. Recommended FlexSwing Termination when AC-coupled

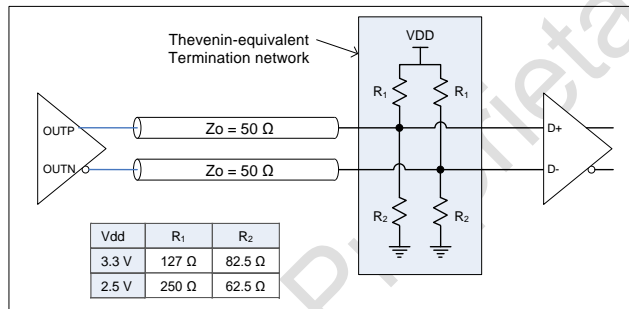


Figure 23. LVPECL and FlexSwing DC-coupled Load Termination with Thevenin Equivalent Network^[14]

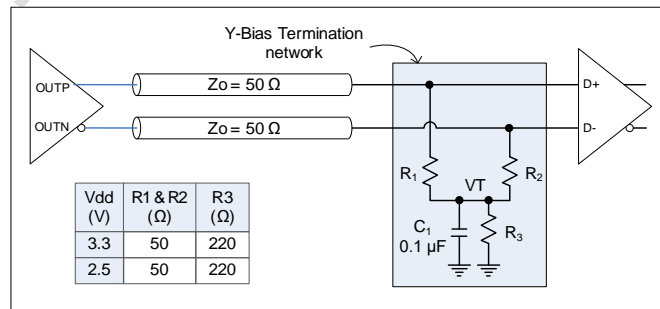


Figure 24. LVPECL and FlexSwing with Y-Bias Termination

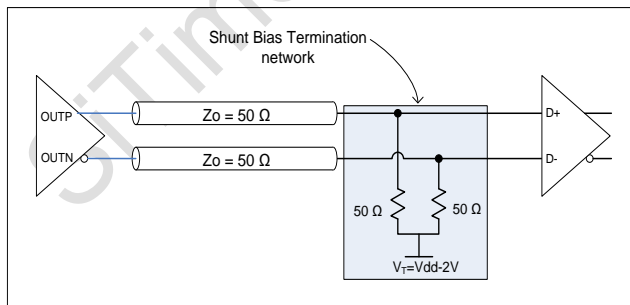


Figure 25. LVPECL and FlexSwing with DC-coupled Parallel Shunt Load Termination

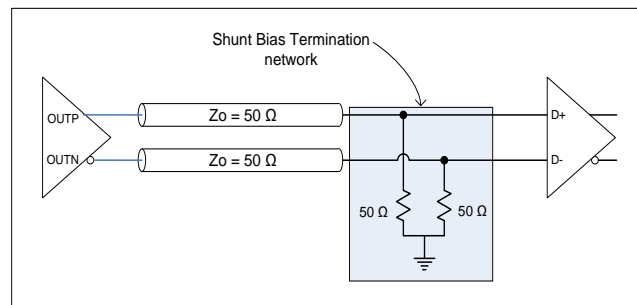
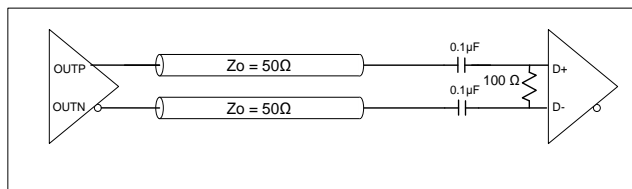
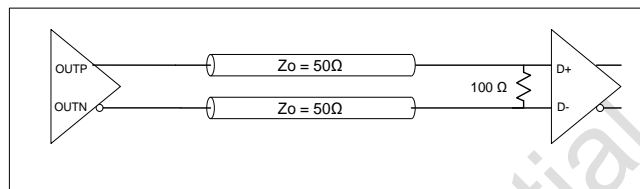
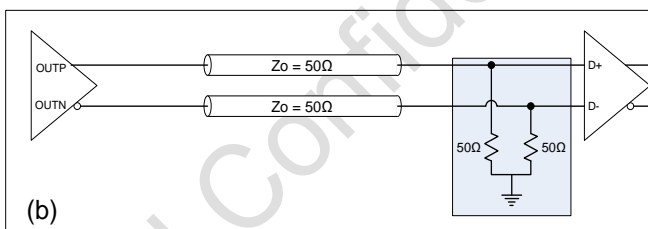
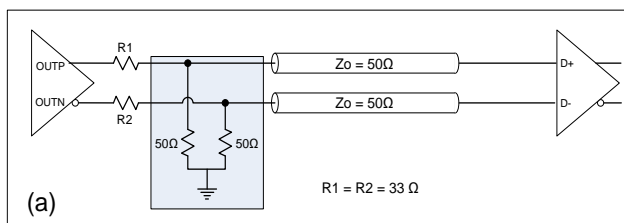
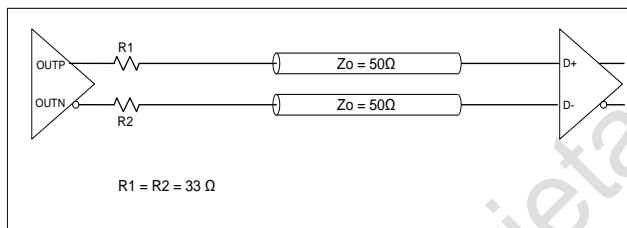


Figure 26. FlexSwing Termination – Only for use with Supply Voltage Order Code “18”

Termination Diagrams (continued)**LVDS, Supply Voltage: 1.8 V \pm 5%, 2.5 V \pm 10%, 3.3 V \pm 10%, 2.25 V to 3.63 V, 1.71 V to 3.63 V****Figure 27. LVDS AC Termination****Figure 28. LVDS DC Termination at the Load****HCSL, Supply Voltage: 1.8 V \pm 5%, 2.5 V \pm 10%, 3.3 V \pm 10%, 2.25 V to 3.63 V, 1.71 V to 3.63 V****Figure 29. (a) HCSL Source Termination and (b) HCSL Load Termination****Low-power HCSL, Supply Voltage: 1.8 V \pm 5%, 2.5 V \pm 10%, 3.3 V \pm 10%, 2.25 V to 3.63 V, 1.71 V to 3.63 V****Figure 30. Low-power HCSL Termination****Notes:**

13. [Contact SiTime](#) for optimum R_B values for FlexSwing options.
14. [Contact SiTime](#) for optimum R_1 and R_2 values for FlexSwing options.

Operating Temperature and Thermal Characteristics**Table 13. Operating Temperature and Thermal Characteristics**

Parameters	Symbol	Min.	Typ.	Max.	Unit	Condition
Ambient Temperature	TA	-40		105	°C	Automotive Grade 2 Temperature Range
	TA	-40		125	°C	Automotive Grade 1 Temperature Range
Junction Temperature	TJ			140	°C	
Thermal Resistance Junction to Ambient	θ_{JA}		25.50		°C/W	Still Air
			20.80		°C/W	Air Flow 1m/s
			19.60		°C/W	Air Flow 2m/s
Thermal Resistance Junction to Case	θ_{JC}		8.70		°C/W	
Thermal Resistance Junction to Board	θ_{JB}		7.07		°C/W	
Thermal Resistance Junction to Top Center	ψ_{JA}		0.20		°C/W	

SiT91281 Low Jitter, 4-Output, AEC-Q100 MEMS Clock Generator**Table 14. Absolute Maximum Limits**

Attempted operation outside the absolute maximum ratings may cause permanent damage to the part. Actual performance of the IC is only guaranteed within the operational specifications, not at absolute maximum ratings.

Parameter	Min.	Max.	Unit
Storage Temperature	-65	150	°C
V _{DD}			V
Electrostatic Discharge, HBM 100 pF, 1.5 kΩ	–	2000	V
Electrostatic Discharge, CDM	–	750	V
Latch up tolerance		JESD78 compliant	
Mechanical Shock Resistance, ΔF/F		10	kG
Mechanical Vibration Resistance, ΔF/F		70	G
Soldering Temperature (follow standard Pb free soldering guidelines)	–	260	°C
Junction Temperature ^[15]	–	150	°C

Note:

15. Exceeding this temperature for extended period of time may damage the device.

Table 15. Thermal Consideration^[16]

Package	θJA, 4 Layer Board (°C/W)	θJA, 2 Layer Board (°C/W)
4 x 4 mm	TBD	TBD

Note:

16. Refer to JESD51 for θJA and θJC definitions, and reference layout used to determine the θJA and θJC values in the above table.

Table 16. Maximum Operating Junction Temperature^[17]

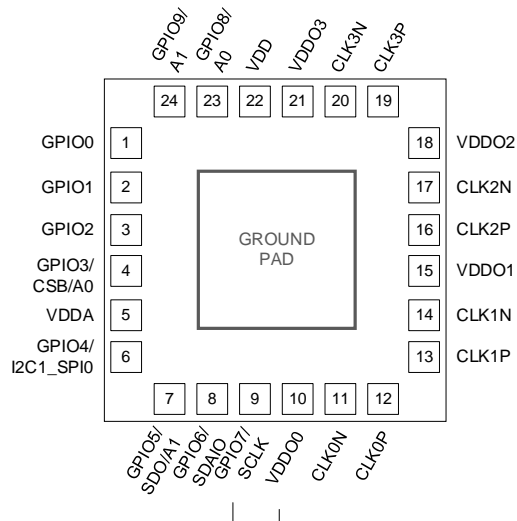
Max Operating Temperature (ambient)	Maximum Operating Junction Temperature
125°C	150°C

Note:

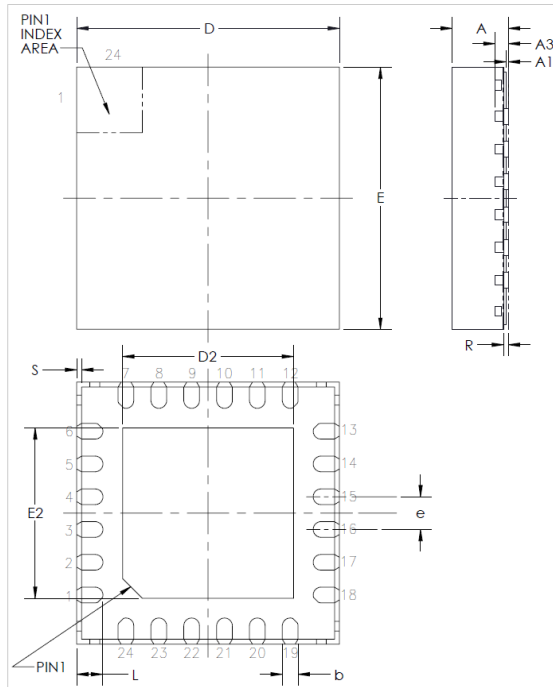
17. Datasheet specifications are not guaranteed if junction temperature exceeds the maximum operating junction temperature.

Table 17. Environmental Compliance

Parameter	Test Conditions
Mechanical Shock Resistance	MIL-STD-883F, Method 2002
Mechanical Vibration Resistance	MIL-STD-883F, Method 2007
Temperature Cycle	JESD22, Method A104
Solderability	MIL-STD-883F, Method 2003
Moisture Sensitivity Level	MSL3 @260°C

Package Pin-Out and Description (Preliminary)**Figure 31. Top View****Table 18. Pin Description**

Pin Name	I/O Type	Pin#	Pull-up (kΩ)	Pull-down (kΩ)	Function	Comments
GPIO0	I	1			Programmable Input	
GPIO1	I/O	2			Programmable Input / Output	
GPIO2	I/O	3			Programmable Input / Output	
GPIO3/CSB/A0	I/O	4			Programmable Input / Output / SPI Chip Select / I2C A0 Address bit	
VDDA	PWR	5			Analog Power Supply	
GPIO4/I2C1_SPI0	I/O	6			Programmable Input / Output / Select between SPI or I2C	
GPIO5/SDO/A1	I/O	7			Programmable Input / Output / SPI Data Output (SDO) / I2C A1 Address bit	
GPIO6/SDAIO	I/O	8			Programmable Input / Output / SPI Input Data (SDI) / I2C Data (SDA)	
GPIO7/SCLK	I/O	9			Programmable Input / Output / SPI / I2C Clock	
VDDO0	PWR	10			Supply Voltage for CLK0	
CLK0N	O	11			Differential / LVCMOS Clock Output	
CLK0P	O	12			Differential / LVCMOS Clock Output	
CLK1P	O	13			Differential / LVCMOS Clock Output	
CLK1N	O	14			Differential / LVCMOS Clock Output	
VDDO1	PWR	15			Supply Voltage for CLK1	
CLK2P	O	16			Differential / LVCMOS Clock Output	
CLK2N	O	17			Differential / LVCMOS Clock Output	
VDDO2	PWR	18			Supply Voltage for CLK2	
CLK3P	O	19			Differential / LVCMOS Clock Output	
CLK3N	O	20			Differential / LVCMOS Clock Output	
VDDO3	PWR	21			Supply Voltage for CLK3	
VDD	PWR	22			Digital Power Supply	
GPIO8/A0	I/O	23			Programmable Input / Output / SPI Chip Select / I2C A0 Address bit	
GPIO9/A1	I/O	24			Programmable Input / Output / SPI Chip Select / I2C A1 Address bit	

Dimensions and Patterns**Package Size – Dimensions (Unit: mm)**

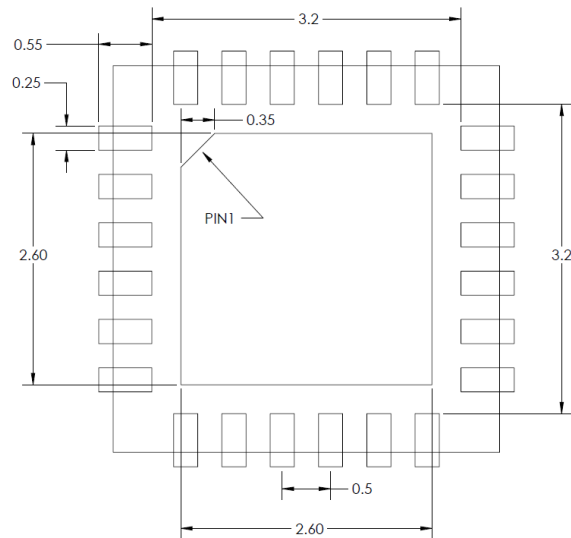
	SYMBOL	MIN	NOM	MAX
TOTAL THICKNESS	A	0.80	0.85	0.90
STAND OFF	A1	0.00	0.035	0.05
SUBSTRATE THICKNESS	A3	0.203	ref	
BODY SIZE	X	D	4.00	BSC
	Y	E	4.00	BSC
EXPOSED PAD	X	D2	2.50	2.60 2.70
	Y	E2	2.50	2.60 2.70
LEAD PITCH	e	0.50	BSC	
LEAD WIDTH	b	0.19	0.24	0.29
LEAD LENGTH	L	0.30	0.40	0.50
HALF-CUT DEPTH	R	0.075	---	---
HALF-CUT WIDTH	S	---	---	0.075

NOTE

1. ALL DIMENSIONS IN MM



PKG INFO		DRAWING NO.	
24L PQFW 4.00X4.00X0.85 mm		POD-093-PQFW-024-T04040	
DATE	12/05/2023	REV	SHEET
		B02	1 of 1

Recommended Land Pattern – Dimensions (Unit: mm)**Note: All units in mm.**

PKG INFO		SPL DRAWING NO.	
24L PQFW 4.0X4.0 mm		SPL-093-PQFW-024-T04040	
DATE	12/05/2023	REV	SHEET
		A01	1 of 1

Additional Information

Table 19. Additional Information

Document	Description	Download Link
Manufacturing Notes	Tape & Reel dimension, reflow profile and other manufacturing related info	https://www.sitime.com/sites/default/files/gated/Manufacturing-Notes-for-SiTime-Products.pdf
Qualification Reports	RoHS report, reliability reports, composition reports	http://www.sitime.com/support/quality-and-reliability
Performance Reports	Additional performance data such as phase noise, current consumption, and jitter for selected frequencies	http://www.sitime.com/support/performance-measurement-report
Termination Techniques	Termination design recommendations	http://www.sitime.com/support/application-notes
Layout Techniques	Layout recommendations	http://www.sitime.com/support/application-notes
ECCN #: EAR99	Five-character designation used on the Commerce Control List (CCL) to identify dual use items for export control purposes.	
HTS Classification Code: 8542.39.0000	A Harmonized Tariff Schedule (HTS) code developed by the World Customs Organization to classify/define internationally traded goods.	

SiT91281 Low Jitter, 4-Output, AEC-Q100 MEMS Clock Generator**Revision History****Table 20. Revision History**

Version	Release Date	Change Summary
0.0	2-Jun-2022	Initial version
0.1	6-Jun-2022	Spec. updates and Pin out changes
0.2	7-Jul-2022	Additional updates on features, descriptions, etc.
0.21	25-Jul-2022	Added Ordering Information and TOC
0.25	4-Feb-2023	Updated Electrical Characteristics, Output Type Specifications and Test Conditions
0.26	15-Feb-2023	Functional Description, Monitoring and General-Purpose Inputs
0.27	3-Mar-2023	Updated Features, Electrical Characteristics, Additional Information, General Purpose Inputs
0.28	3-Mar-2023	Updated Ordering Information with Freq Stability code Organized Additional Information table links
0.31	10-Oct-2023	Updated Electrical Characteristics, Test Setup Diagrams, GPIO Table
0.32	20-Oct-2023	Updated GPIO Table
0.33	10-Nov-2023	GPIO inputs configurable active high and low
0.34	06-Dec-2023	Updated Package Drawings, GPIO tables, pin descriptions
0.35	19-Dec-2023	Updated Electrical Characteristics and Functional Description

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